

SmartPlant Instrumentation Technical User Forum P2C2 (Houston SPI TUF) Meeting	February 13, 2018 8:00 am Emerson Process Management
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Attendees	24 Members in attendance 18 Online Connections	Copied To	Houston SPI LTUF Website http://www.spi-Ituf.org
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Called By	John Dressel	Prepared By	John Dressel
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Item	Topic	Notes	Action/Due
1	Welcome 8:00	Welcome & Safety Moment <ul style="list-style-type: none"> • Welcome & Introduction Tom Powers, Emerson • Safety Moment Tom Powers, Emerson 	
2	Chairman's Notes 8:05	Announcements and Introductions John Dressel, Fluor <ul style="list-style-type: none"> • Introductions – All attendees • Hexagon 2017 to be June 13-16 with the GTUF on June 12 at the Venetian Las Vegas, NV. 	
3	Officers Election 8:10	Election of Officers <ul style="list-style-type: none"> • John Dressel, LTUF Chair • Telephone: +1.281.263.2764 • John.Dressel@fluor.com • Blake Biernacki, LTUF Vice-chair • Telephone: +1.832.540.8465 • Blake.Biernacki@ProLytX.com • Dee Dee Honea, LTUF Secretary • Telephone: +1.979.230.8613 • Denise.Honea@Eichleay.com 	
4	Presentation 8:10	Hexagon API's Overview David Kaiser, Intergraph 5-Phase Plan <ul style="list-style-type: none"> • Phase 0 - Windows 10 compatible .NET migration - June 2018 • Phase 1 - SaaS Admin - June 2018 (1st release) • Phase 2 - SaaS Read-only (Web APIs) - 1H 2018 (1st release) • Phase 3 - SaaS Engineering Data Entry (Write Web APIs) In-progress • Phase 4 - SaaS Graphical Data Entry In-research SmartPlant Instrumentation – Roadmap <ul style="list-style-type: none"> • Intergraph SmartPlant Instrumentation: Q2 2018 • New Backup/Restore platform • New and enhanced upgrade technology • New .NET ESR <ul style="list-style-type: none"> ○ Same Explorers as in main app • WebAPIs <ul style="list-style-type: none"> ○ First release: Q1 2018 ○ Baseline: SPI v2016 ○ Continuous releases 	

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		<p>Web API with Postman</p> <ul style="list-style-type: none"> • Web API –Sample Using Postman a complete API development environment for Web API developers <p>Web API with Power BI</p> <ul style="list-style-type: none"> • Power BI - Sample display of an SPI API desktop display of Instrument Table Fields in real time • Power BI - Sample display of a SPI interactive dashboard for accessing data in real time 	
5	Presentation 9:00	<p>SPI Blending Module Dennis Cooley, CooleyCore</p> <p>COOLEYCORE – PROFILE HIGHLIGHTS Incorporated: January, 2008 Head Office: Calgary, Canada Products: software applications and services Industries: Oil & Gas, Chemicals, Plastics Partnerships: Hexagon CooleyCore software is certified by our Premier Partner, Hexagon. Website: http://smartstore.cooleycore.com/</p> <p>SCENARIOS THAT LEAD TO MULTIPLE DATABASES MAJORITY OF COMPANIES HAVE MORE THAN ONE DATABASE Common reasons for multiple SPI databases include:</p> <ul style="list-style-type: none"> • Multiple different sites – each with their own database • Multiple EPC’s engineering large facilities; segregated scopes • Multi-phase facility expansions; executed with different SPI versions • Major project being executed in remote location; performance is key – centralized hosting is considered risky • Mix of above <p>WHY BLEND DATABASES? REDUCES COSTS & CONFUSION</p> <ul style="list-style-type: none"> • Reduce confusion; end users can locate and gather information with greater ease • Facilitates easier integration between applications • Take advantage of great designs and replicate across facilities that would otherwise not be possible • Standardizing design; improves the quality of the design, and deliverables; • Reduces time executing projects • Reduce User Management – fewer SPI accounts and user groups • Reduces IT costs & upgrade costs; prod and non prod environments are reduced <p>BEACONSUITE BLENDING AUTOMATION – DELIVERS PROVEN – COST-EFFECTIVE SOLUTION</p> <ul style="list-style-type: none"> • CooleyCore has developed blending automation that addresses several challenges. • Blend automation works with both Engineering mode and 	

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		<p>Owner Operator mode Databases</p> <ul style="list-style-type: none"> • Extract Seed & Blend just the Seed/Standards to a new Domain <p>DATABASE / DOMAIN BLENDING – YOU CAN DO IT!</p> <ul style="list-style-type: none"> • We Offer Services; if you would like we can execute the blends as a service • We Offer Training; CooleyCore offers training • Commercial Grade Solution; we have software that you can license, empowering you to do the blends with internal resources <p>DATABASE BLEND – HIGH QUALITY RESULTS FEATURES:</p> <ul style="list-style-type: none"> • Reports differences between standards used within the source and target databases. An intelligent auto mapping algorithm efficiently maps pick-list selections (e.g. Instrument Types) • Transforms the source database standards while blending the data into the target database • Leaves the source database untouched while blending its data into the target database • Identifies bad data prior to blending the databases and in some cases, fixes the bad data (e.g. Plant, Area, Unit assignments) <p>ALIGN, TRANSFORM, BLEND STANDARDS STANDARDS EXIST IN EACH SPI MODULE Standards exist in the form of:</p> <ul style="list-style-type: none"> • Pick-lists e.g. Instrument Types • Forms e.g. Instrument Specifications • Layouts e.g. Loop ESL Layouts <p>DATABASE I DOMAIN BLENDING - SUCCESS SAFELY CLEAN UP INCORRECT PAU ASSIGNMENTS Blend Project Execution</p> <ul style="list-style-type: none"> • Please contact us to help with your Blend project • CooleyCore's Beaconsuite software application contains 15 different modules • Each module can be licensed individually – users can license just what they need • Program Manager: Tim Anstett Email: Tim.Anstett@cooleycore.com Ph: 403 818 8276 • President: Dennis Cooley Email: Dennis.Cooley@cooleycore.com Ph: 403 975 9797 • Chief Innovation Officer: Zur Bar Email: Zur.Bar@cooleycore.com <p>BLENDING SPI DATABASES - Questions</p>	

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6	Presentation 9:20	<p>CR Ranking Website Presentation Dennis Cooley, CooleyCore</p> <p>SMARTPLANT IDEAS DELIVER INNOVATION PRESENTATION SUMMARY</p> <ul style="list-style-type: none"> • When Is Innovation Needed • Steward To Values • SmartPlant Idea Ranking Websites • SmartPlant Community • How The Ranking Websites Work • Shaping Change – Submit Your Ideas • Blog Your Opinion On The Ideas • Ranking Websites Deliver Innovation <p>WHEN IS INNOVATION IS NEEDED SOMETIMES THE NEED IS CLEAR SOMETIMES THE SOLUTION IS CLEAR</p> <p>INNOVATION HELPS US STEWARD STEWARD TO CORE VALUES</p> <ul style="list-style-type: none"> • Protect our data • Access to the right information • Good Performance • Revision Management / History Tracking <p>SMARTPLANT WEBSITES OPEN TO MULTIPLE COMMUNITIES</p> <p>www.sptuf.com</p> <p>WEBSITE COVERAGE INCLUDES</p> <ul style="list-style-type: none"> • Meeting Minutes • Idea Rankings • Community Idea Sharing <p>INTERGRAPH BUILDS YOUR GREAT IDEAS</p> <ul style="list-style-type: none"> • Submit / Add Your Idea <p>ALL IDEAS ARE WELCOME</p> <ul style="list-style-type: none"> • Fast and easy to fill in form <p>RANKING TABULATION IS AUTOMATED</p> <ul style="list-style-type: none"> • Quickly Understand Rankings <p>PRIORITIZE YOUR RANKINGS</p> <ul style="list-style-type: none"> • Fast and easy to rank ideas <p>YOUR PARTICIPATION IS KEY</p> <ul style="list-style-type: none"> • Make a difference <p>RANKING WEBSITES DELIVER INNOVATION Shaping Change:</p>	

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		<ul style="list-style-type: none"> • Great ideas result in job satisfaction • Great ideas deliver efficiencies • Great ideas enable you & your company to compete • Great ideas are implemented by Intergraph ® • Your ideas and rankings make a difference <p>How can we get even more participation in this process? Email your ideas to: Dennis.Coolley@cooleycor.com</p> <p>Questions?</p>	
7	Presentation 10:00	<p>WIRING CHARM I/O IN SPI Emeka Nwagbara, Fluor</p> <p>Wiring CHARM I/O in SPI Introduction</p> <ul style="list-style-type: none"> • The User Experience on a Project with over 50,000 I/O 	

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		<ul style="list-style-type: none"> • While several wiring methods were used on the project, this presentation will focus on the use of Electronic marshalling • Reasons for using Electronic Marshalling on the Project: <ul style="list-style-type: none"> ○ Emerson was the MIC and the MAC on the Project ○ Emerson DeltaV DCS and SIS systems were used ○ The DeltaV - SPI Interface was proposed for the Project ○ Primary I/O was CHARacterization Module (CHARM) I/O ○ Project Configuration of CHARM I/O employed: <ul style="list-style-type: none"> ○ Standardized Remote CHARM Field Enclosures ○ Redundant Fiber Optic Network to Control Centers ○ Wiring and Loop Diagrams to be SPI Enhanced Reports <p>Benefits of using Electronic Marshalling</p> <ul style="list-style-type: none"> • Redundant Ethernet topology • Elimination of homerun wiring • Reduced overall System Costs • Flexibility: <ul style="list-style-type: none"> ○ Any type of I/O at any location ○ Reconfigurable at any time ○ Standard Ethernet hardware ○ Remote I/O Eliminate Wiring ○ Plug and Play Configuration ○ Single Channel Granularity ○ Each I/O Card can serve 4 controllers <p>DeltaV SPI Interface Workflow:</p> <ul style="list-style-type: none"> • Diagram of an overview of the workflow that is supported by the interface <p>Download I/O Definitions Into SPI</p> <ul style="list-style-type: none"> • The DeltaV I/O definitions are maintained by Emerson but downloaded using a link from Intergraph: http://forms.intergraph.com/Download_DeltaV_Definition_Files • This assures the definitions are the latest and provide information to improve the data transfer process • The downloaded definitions appear in the Reference Explorer as SPI Objects <p>What is Downloaded?</p> <ul style="list-style-type: none"> • DeltaV Conventional I/O Definitions • DeltaV S Series I/O Definitions • Types CHARM Card Definitions: <ul style="list-style-type: none"> ○ AI 4-20 mA HART ○ RTD ○ Thermocouple / mV ○ AI 0-10V DC Isolated ○ AO 4-20 mA HART ○ DI NAMUR ○ DI 24V DC low-side sense ○ DI 24V DC Isolated ○ DO 24V DC High Side ○ DO 100mA Energy Limited ○ DO 24V DC Isolated ○ 24V DC Power 	

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		<ul style="list-style-type: none"> ○ DI 120V AC Isolated ○ DI 120V AC Isolated Plus ○ DI 230V AC Isolated ○ DO V AC Isolated <p>Reference I/O Definitions</p> <ul style="list-style-type: none"> ● Reference I/O Definitions include: <ul style="list-style-type: none"> ○ Wiring Equipment <ul style="list-style-type: none"> ▪ Name ▪ Description ▪ Manufacturer ○ Terminal Strip <ul style="list-style-type: none"> ▪ Name ▪ Panel Name ▪ Manufacturer ○ Terminals <ul style="list-style-type: none"> ▪ 2 or 4 Terminals for connections ● Note: We eliminated unused CHARM cards from Reference Explorer ● Reference I/O can be used to build CHARM I/O Card (CIOC) Panels in the Wiring Module <p>CHARM I/O Card (CIOC) Configuration</p> <ul style="list-style-type: none"> ● Each Field Panel has a redundant CIOC Carrier ; I/O Cards with redundant Ethernet Communications Module and 24VDC Power Supply ● CHARM Base Plate; DIN rail-mounted with power, bus connectors, and Supports 12 CHARMs per Base Plate ● CHARM Terminal Block - removable terminal block providing connections to field wiring and physical latch for CHARM ● CHARMs - Characterization Module for each field signal - Provides basic analog to digital conversion and signal isolation to the redundant communication bus ● DIN rail mount for all CIOC components <p>CHARM I/O Card (CIOC) FIE/RIE Wiring Issue</p> <ul style="list-style-type: none"> ● Shown below is the proposed DCS FIE/RIE Hierarchy per Emerson CHARM white paper <ul style="list-style-type: none"> ○ Panel ○ Rack ○ Slot (Branch) <ul style="list-style-type: none"> ▪ CHARM ▪ Terminal Strip ▪ Channel ▪ Terminals ● However this hierarchy resulted in the SPI Terminal Strip wiring report with adjacent connections having only one signal per drawing <p>CHARM I/O Card (CIOC) FIE/RIE Wiring Answer</p> <ul style="list-style-type: none"> ● Actual Project DCS FIE Hierarchy <ul style="list-style-type: none"> ○ Panel ○ Rack ○ Slot ○ CHARM ○ Terminal Strip (Branch) 	

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		<ul style="list-style-type: none"> ▪ Channel ▪ Terminals • The Terminal Strip report now showed all 12 CHARM channels • Con: The CHARM was above the branch now and lost unique CHARM data per channel <p>CHARM Field Enclosures</p> <ul style="list-style-type: none"> • Benefits of using Field Enclosures: <ul style="list-style-type: none"> ○ Allows for Electronic Marshalling and Remote I/O in one Cabinet ○ Optimizes use of CHARM I/O Technology ○ Reduce Overall System Footprint ○ Eliminates I/O Home Run Cables ○ Reduce design engineering workhours ○ Safe for Hazardous Areas ○ Fully Vendor Tested and Documented Enclosures • Field Enclosures Equipped as Follows: <ul style="list-style-type: none"> ○ Power distribution and isolation components for primary and secondary 24V DC Power to CHARM I/O Cards. ○ AC power feeds with redundant AC/DC 24V DC bulk power supplies. ○ Grounding bars for CG (Chassis Ground) and DC Reference Ground ○ Wire Ducts and Name Plates ○ CIOC Carriers, Base Plates and Terminals. <p>CHARM Cards</p> <ul style="list-style-type: none"> • Analog Input 4-20 mA HART CHARM Characteristics <ul style="list-style-type: none"> ○ 2 wire Loop Powered ○ Signal - 4-20 mA with or without HART ○ Impedance - 250 Ω \pm1% ○ Accuracy - 0.1% of span (0-60°C) ○ Repeatability - 0.05% of span ○ Resolution - 16 bit A/D converter ○ Calibration - None required ○ Loop Power - 15 V at 20 mA @ 24V DC • Analog Input 4-20 mA HART CHARM Characteristics <ul style="list-style-type: none"> ○ 2 wire Field Powered ○ Signal - 4-20 mA with or without HART ○ Impedance - 250 Ω \pm1% ○ Accuracy - 0.1% of span (0-60°C) ○ Repeatability - 0.05% of span ○ Resolution - 16 bit A/D converter ○ Calibration - None required ○ Field Powered • Analog Input 4-20 mA HART CHARM Characteristics <ul style="list-style-type: none"> ○ 3 wire CHARM Powered ○ 24V DC Power CHARM ○ Max Power 24V DC at 20mA ○ Signal - 4-20 mA with or without HART ○ Impedance - 250 Ω \pm1% ○ Accuracy - 0.1% of span (0-60°C) 	

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		<ul style="list-style-type: none"> ○ Repeatability - 0.05% of span ○ Resolution - 16 bit A/D converter ○ Calibration - None required ● Analog Output 4-20 mA HART CHARM <ul style="list-style-type: none"> ○ Signal Range: 4 to 20 mA ○ Full Signal Range: 0 to 24 mA ○ Accuracy - 0.25% of span (0 to 60°C) ○ Accuracy - 0.5% of span (-40 to 70°C) ○ Resolution 16-bit D/A converter ○ Calibration None required ○ Available Field Power 20 mA at 15V DC supply into 750 Ω load ● RTD Input CHARM <ul style="list-style-type: none"> ○ 2 wire RTD ○ Operating Range - -200 to 850°C ○ Temperature drift - ± 0.02°C/°C ○ Accuracy - ± 0.25°C ○ Repeatability - 0.05% of span ○ Resolution - 24 bit A/D converter ○ Calibration - None required ○ Common Mode Rejection - 90dB typical ○ Open Sensor Detection ● RTD Input CHARM <ul style="list-style-type: none"> ○ 3 wire RTD ○ Operating Range - -200 to 850°C ○ Temperature drift - ± 0.02°C/°C ○ Accuracy - ± 0.25°C ○ Repeatability - 0.05% of span ○ Resolution - 24 bit A/D converter ○ Calibration - None required ○ Common Mode Rejection - 90dB typical ○ Includes Open Sensor Detection ● RTD Input CHARM <ul style="list-style-type: none"> ○ 4 wire RTD ○ Operating Range - -200 to 850°C ○ Temperature drift - ± 0.02°C/°C ○ Accuracy - ± 0.25°C ○ Repeatability - 0.05% of span ○ Resolution - 24 bit A/D converter ○ Calibration - None required ○ Common Mode Rejection - 90dB typical ○ Includes Open Sensor Detection ● Discrete Input 24 V DC low-side sense (dry contact) CHARM <ul style="list-style-type: none"> ○ Sensor Types 24V DC - Dry Contacts ○ On Detection Level - >2.25 mA ○ Off Detection Level - <1.75 mA ○ Channel Impedance - 4.8 KΩ ○ Wetting Voltage - 22.5Volts ○ Configurable Channel Types - Discrete Input or Pulse Co 	

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		<ul style="list-style-type: none"> • Discrete Output 24V DC High-Side CHARM <ul style="list-style-type: none"> ○ On State Rating - 100 mA @ 24V DC ○ Off State Leakage Current - 1 mA Line Fault Detection „ „ ○ Short circuit: <50 Ω load ○ Good status: 240 Ω to 10 kΩ load ○ Open circuit: >20 kΩ load ○ Configurable Output Behavior „ „ ○ Momentary Output ○ Continuous Pulse Output • 24V DC Power CHARM <ul style="list-style-type: none"> ○ Device Type 24V DC Power output ○ Status for Power Good >10V DC ○ Status for Power Bad <5V DC ○ Isolation - Status read back circuitry is optically isolated and factory tested to 1000V DC. ○ Field Circuit Protection „ 2 Amp fuse ○ CHARM Power - 12 mA max ○ Available Power - 1.01 Amps max <p>CIOC Strip with Adjacent Terminals Report</p> <ul style="list-style-type: none"> • Enhanced CIOC Strip Report with adjacent Terminals shows: <ul style="list-style-type: none"> ○ Field Wiring from the instrument to the CIOC ○ Two Page report with 9 I/O on first and 3 on the second ○ Cable Names ○ Wire Colors ○ Panel Number ○ Strip Number ○ Channel Numbers ○ Terminal Numbers ○ CS Tag Numbers Displays per set Preferences <p>CIOC Loop Diagram Example</p> <ul style="list-style-type: none"> • Due to lack of Marshalling Strip, Enhanced SPI Loop Diagram typically only shows the Device Panels Instrument and COIC Terminations (Loops may not be needed) <p>Using Electronic Marshalling Conclusion</p> <ul style="list-style-type: none"> • CIOC is Configurable for: <ul style="list-style-type: none"> ○ Basic Process Control Systems (BPCS) ○ Safety Instrumented Systems (SIS) ○ Intrinsically Safe (IS) Systems • CIOC Can be RIE or Field Mounted • Instrument Wiring to CIOC can be Direct or by Junction Boxes and Homerun Cables • Eliminates Marshalling Cabinets • Eliminates need for Loop Diagrams • Potential to replace other wiring methods <p>Questions</p>	
8	Presentation	<p>PIP DMDIM001 SPI SIG</p> <p style="text-align: right;">Gene Haney, CB&I</p>	

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	10:30	<p>PIP DMDIM001 Instrument Metadata Requirements</p> <p>Instrument Design Tool Configuration (IDTC)</p> <ul style="list-style-type: none"> • Purpose and Method: • Facilitate Data Sharing • Create Generic Practice • Define a 'Harmonized' Mapping • Provide Autonomy to Each Data Contributor • Review industry standards (e.g., SPI, ISA, OSI, ISO, NE-100 Etc...) and incorporate instrument datasheets. • PIP IDTC Task Team has identified 500+ data elements associated with instrument specification data for instruments of the Flow, Level, Pressure and Temperature process functions • They are just now adding Control Valve data elements to the specification • Only 20% of these data elements have a defined data field in the SPI schema. • Houston SPI LTUF is conducting a IDTC Special Interest Group with the following plan of action: <ul style="list-style-type: none"> ○ Identify data elements from list that exist in SPI ○ Review, consolidate, expand list of data elements not in SPI ○ Assist in developing the Control Valve data elements to the IDTC ○ Provide feedback to the PIP DMDIM001 IDTC committee ○ Provide recommended schema changes to Intergraph • The Special Interest Group (SIG) was formed to review the 'missing' fields and make a recommendation to Intergraph pending rebuild of the Spec Module in SPI • The SPI was introduced to Hexagon PPM at HxGN 2017 in Las Vegas and received with much interest: <ul style="list-style-type: none"> ○ The SmartPlant Instrumentation Spec Module is undergoing a major update to eliminate the need for Infomaker ○ Hexagon is driving an initiative to include WEB API's for external integration in all the tools and this requires a structured Data Dictionary as the bases of all Spec Sheets <p>Current Houston SPI LTUF SIG Members: Gene Haney, CB&I (SIG Chair) Bob Zerda, PIP Alex Koifman, F.I.R.S.T. CONVAL Betty Alexander, JGC Chris Cordes, Covestro Guillermo Vigna, Endress+Hauser John Dressel, Fluor Kory Johnson, Marathon Nezar Faitouri, Mangan, Inc.</p> <ul style="list-style-type: none"> • The efforts of this SIG are ongoing and intended to bring more consistency to the SPI Spec Data Dictionary and PIP DMDIM001 • Gene Haney is seeking more members and participation in 	

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		the SIG	
9	LTUF Forum 10:55	Forum Discussion Topics <ul style="list-style-type: none"> • Data Centric Engineering • SPI Integration Issues • SPI 2016 Upgrades • SPI 2016 EDE Tips and Tricks 	All Attendees
10	Close 11:00	<ul style="list-style-type: none"> • The next meeting is scheduled for May 15, 2018 at Jacobs • John Dressel closed Meeting and we adjourned to Emerson Equipment Display Area 	